COMBINED DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP PACKAGE

SEMICOMPOCI	ok cim having bond i	ADS AND MOLIT-CIM TAC.	KACL	
, the specification	of which:			
	is attached hereto. was filed on and was amended on with amendments throug	_ as Application No(if applicable) h (if applicable).		
		understand the contents of the ab by any amendment referred to a		tifie
	•	mation which is material to the p Code of Federal Regulations, Se	-	lity
(a)-(d) or §365(b) of any PCT international United States of A for patent or inventional Control of the state	of any foreign application(s) ational application which des merica, listed below and hav	under Title 35, United States Confor patent or inventor's certification ignated at least one country other also identified below any foreing Tinternational application having ority is claimed:	te, or §36 r than the gn applic	65(a) e cation
Prior Foreign App	lication(s)		Clain Priori	_
2001-0041154 (Number)	Republic of Korea (Country)	10 July 2001 (Day/Month/Year Filed)	∑ Yes	No
2002-0003030 (Number)	Republic of Korea (Country)	18 January 2002 (Day/Month/Year Filed)	⊠ Yes	No
	aim the benefit under Title 3: visional application listed belo	5, United States Code, Sec. 119(ow:	e) of any	
Provisional Application No.		Filing Date		
				

I hereby claim the benefit under Title 35, United States Code, Sec. 120 or §365(c) of any PCT international application designating the United States of America listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, Sec. 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, Sec. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Application No.) (Filing Date) (Status) (patented, pending, abandoned)

I hereby appoint the following attorneys to prosecute the application, to file a corresponding international application, to prosecute and transact all business in the Patent and Trademark Office connected therewith:

20575

20575

PATENT TRADEMARK OFFICE

Attorney Name	Registration No.
Tanama C. Maraan	26 490
Jerome S. Marger	26,480
Alexander C. Johnson, Jr.	29,396
Alan T. McCollom	28,881
James G. Stewart	32,496
Stephen S. Ford	35,139
Julie L. Reed	35,349
Walter D. Fields	37,130
Gregory T. Kavounas	37,862
Scott A. Schaffer	38,610
Joseph S. Makuch	39,286
James E. Harris	40,013
Kevin S. Ross	42,116
Graciela G. Cowger	42,444
Ariel Rogson	43,054
Craig R. Rogers	43,888
Kurt M. Rylander	43,897
Hillary Brooks	45,815
Clifford D. Weston	48,307

Direct all telephone calls to <u>Alan T. McCollom</u> at (503) 222-3613 and send all correspondence to:

MARGER JOHNSON & McCOLLOM, P.C. 1030 S.W. Morrison Street

Portland, Oregon 97205

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Young-Hee SONG				
Inventor's signature: Young-Hee SONG June, w, 62 (Date)				
Residence: Kyunggi-do, Republic of Korea				
Citizenship: Republic of Korea				
Post Office address: 502-1002, Samsing-5-APT, Pungdeokcheon-Ri, Suji-Eup, Yongin-City, Kyunggi-do, Republic of Korea				
Full name of second joint inventor: Il-Heung CHOI				
Inventor's signature: ZL. HEUNG, CHO2 June. 2/. O (Date)				
Residence: Kyunggi-Do, Republic of Korea				
Citizenship: Republic of Korea				
Post Office address: 439-601, Samsung APT, Yeongtong-Dong, Paldal-Gu, Suwon-City, Kyunggi-Do, Republic of Korea				
Full name of third joint inventor: Jeong-Jin KIM				
Inventor's signature: Jeong-Jin Kim June, 20 w (Date)				
Residence: Chungcheongnam-Do, Republic of Korea				
Citizenship: Republic of Korea				
Post Office address: 303-702, Jugong-7-APT, Sangyong-Dong, Cheonan-City, Chungcheongnam-Do, Republic of Korea				

Full name of fourth joint inventor: Hae-Jeong SOHN

Inventor's signature: Har Teans Selin June 27 '62 (Date)

Residence: Kyunggi-Do, Republic of Korea

Citizenship: Republic of Korea

Post Office address: 645-1702, Shinwon APT, Yeongtong-Dong, Paldal-Gu, Suwon-City,

Kyunggi-Do, Republic of Korea

Full name of fifth joint inventor: Chung-Woo LEE

Inventor's signature: Chang-how LEZ June. 20, 02 (Date)

Residence: Kyunggi-Do, Republic of Korea

Citizenship: Republic of Korea

Post Office address: 643-901, Shinwon APT, Yeongtong-Dong, Paldal-Gu, Suwon-City,

Kyunggi-Do, Republic of Korea

PATENT APPLICATION Atty's Do. No. 9903-051 Yoon & Lee Ref. No.:

ASSIGNMENT

U.S.A. Patent Application
Sole or Joint
For Inventions Made Outside U.S.A.
Executed With Application

In consideration of the sum of Ten Dollars (10.00) and other good and valuable considerations paid to each of the undersigned, to wit:

- (1) Young-Hee SONG
- (2) Il-Heung CHOI
- (3) Jeong-Jin KIM
- (4) Hae-Jeong SOHN
- (5) Chung-Woo LEE

	X	if	continued	on	separate	page
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the receipt and sufficiency of which are hereby acknowledged by the undersigned who hereby sell(s), assign(s) and transfer(s) unto:

SAMSUNG ELECTRONICS CO., LTD. 416 MAETAN-DONG, PALDAL-KU SUWON-CITY, KYUNGKI-DO REPUBLIC OF KOREA

(hereinafter designated "ASSIGNEE") the entire right, title and interest in and to the invention as defined in 35 USC §100, for the United States of America, the invention entitled:

SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP PACKAGE

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisionals, continuations, substitutes, and reissues thereof; and all resulting patents and the undersigned hereby authorizes and requests the United States Assistant Commissioner of Patents to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

And the undersigned hereby agrees to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

Please sign
concurrently
with Oath or Declaration
and Power of Attorney

SIGNED ON THE DATES INDICATED BESIDE OUR SIGNATURES:

INVENTOR(S)	DATE SIGNED	WITNESSED
(1) Young-Hee SONG Young-Hee SONG	June, 20, 62	
(2) IL. Heung CHOZ II-Heung CHOI	Jume . y or	
(3) Jeong-Jin Kim Jeong-Jin KIM	June so os	
(4) Hae-Jeong Sohn	June 2 62.	: .
(5) Chung-Woo LEE	June . 20. 02	

PLEASE RETURN RECORDED ASSIGNMENT TO:

Alan T. McCollom Marger Johnson & McCollom 1030 S.W. Morrison Street Portland, OR 97205

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

BOX PATENT APPLICATION Assistant Commissioner for Patents Washington, D.C. 20231

Please record the attached original document or copy thereof and return the recorded instrument to the undersigned.

		•			
1.	Name of party(ies) conveying an interest:	Young-Hee SONG, Il-Heung CHOI, Jeong-Jin KIM, Hae-Jeong SOHN and Chung-Woo LEE			
2.	Name and address of party(ies) receiving an interest:	Samsung Electronics Co., Ltd. San 16, Banwoi, ri, Taean-eub, Hwasung-city Kyungki-do KOREA			
3.	Description of the interest conveyed:				
	Assignment Change of Name Security Agreement Merger				
	Date of execution of attached document: June 20, 2002 a	nd June 21, 2002			
4.	Application number(s) or patent number(s). Additional sheet attached? Yes No				
If this c	locument is being filed together with a new application, the	e execution date of the application is: July 9, 2002			
	A. Patent Application No.	B. Patent No.			
5.	Name and address of party to whom correspondence concerning document should be mailed:				
	MARGER JOHNSON & McCOLLOM, P.C. 1030 S.W. Morrison Street Portland, Oregon 97205 Telephone: (503) 222-3613				
6.	Number of applications and patents involved: 1				

Any deficiency or overpayment should be charged or credited to deposit account number 13-1703.

PTO Form 2038 authorizing credit card payment (\$40) is enclosed.

9. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Dated: July 9, 2002

7.

8.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Alan T. McCollom

Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C. 1030 SW Morrison Street Portland, OR 97205 (503) 222-3613

Total number of pages comprising cover sheet and attached assignment: 3



SEPTEMBER 19, 2002

PTAS

MARGER JOHNSON & MCCOLLOM, P.C. ALAN T. MCCOLLOM 1030 S.W. MORRISON STREET PORTLAND, OREGON 97205 Under Secretary of Commerce For Intellectual Property and Director of the United States Patent and Trademark Office Washington, DC 20231 www.uspto.gov



102164846A

UNITED STATES PATENT AND TRADEMARK OFFICE NOTICE OF RECORDATION OF ASSIGNMENT DOCUMENT

THE ENCLOSED DOCUMENT HAS BEEN RECORDED BY THE ASSIGNMENT DIVISION OF THE U.S. PATENT AND TRADEMARK OFFICE. A COMPLETE MICROFILM COPY IS AVAILABLE AT THE ASSIGNMENT SEARCH ROOM ON THE REEL AND FRAME NUMBER REFERENCED BELOW.

PLEASE REVIEW ALL INFORMATION CONTAINED ON THIS NOTICE. THE INFORMATION CONTAINED ON THIS RECORDATION NOTICE REFLECTS THE DATA PRESENT IN THE PATENT AND TRADEMARK ASSIGNMENT SYSTEM. IF YOU SHOULD FIND ANY ERRORS OR HAVE QUESTIONS CONCERNING THIS NOTICE, YOU MAY CONTACT THE EMPLOYEE WHOSE NAME APPEARS ON THIS NOTICE AT 703-308-9723. PLEASE SEND REQUEST FOR CORRECTION TO: U.S. PATENT AND TRADEMARK OFFICE, ASSIGNMENT DIVISION, BOX ASSIGNMENTS, CG-4, 1213 JEFFERSON DAVIS HWY, SUITE 320, WASHINGTON, D.C. 20231.

RECORDATION DATE: 07/10/2002

REEL/FRAME: 013100/0280

NUMBER OF PAGES: 3

BRIEF: ASSIGNMENT OF ASSIGNOR'S INTEREST (SEE DOCUMENT FOR DETAILS).

ASSIGNOR:

SONG, YOUNG-HEE

DOC DATE: 06/20/2002

ASSIGNOR:

CHOI, II-HEUNG

DOC DATE: 06/21/2002

ASSIGNOR:

KIM, JEONG-JIN

DOC DATE: 06/20/2002

ASSIGNOR:

SOHN, HAE-JEONG

DOC DATE: 06/20/2002

ASSIGNOR:

LEE, CHUNG-WOO

DOC DATE: 06/20/2002

ASSIGNEE:

SAMSUNG ELECTRONICS CO., LTD.
SAN 16, BANWOI, RI, TAEAN-EUB,
HWASUNG-CITY
KYUNGKI-DO, REPUBLIC OF KOREA

013100/0280 PAGE 2

SERIAL NUMBER: 10192800

PATENT NUMBER:

FILING DATE: 07/10/2002

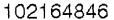
ISSUE DATE:

TONYA LEE, EXAMINER ASSIGNMENT DIVISION OFFICE OF PUBLIC RECORDS

IN THE UNITED STATES PA

BOX PATENT APPLICATION Assistant Commissioner for Patents Washington, D.C. 20231







Please record the attached original document or copy thereof and return the recorded instrument to undersigned.

1. Name of party(ies) conveying an interest: Young-Hee SONG, Il-Heung CHOI, Jeong-Jin KIM,

Hae-Jeong SOHN and Chung-Woo LEE

2. Name and address of party(ies) receiving an interest: Samsung Electronics Co., Ltd.

San 16, Banwoi, ri, Taean-eub, Hwasung-city

Kyungki-do KOREA

3. Description of the interest conveyed:

Assignment Change of Name Security Agreement Merger

Date of execution of attached document: June 20, 2002 and June 21, 2002

4. Application number(s) or patent number(s). Additional sheet attached? Yes No

If this document is being filed together with a new application, the execution date of the application is: July 9, 2002

A. Patent Application No.

B. Patent No.

Name and address of party to whom correspondence concerning document should be mailed: 5.

MARGER JOHNSON & McCOLLOM, P.C.

1030 S.W. Morrison Street Portland, Oregon 97205

Telephone: (503) 222-3613

- 6. Number of applications and patents involved: 1
- 7. PTO Form 2038 authorizing credit card payment (\$40) is enclosed.
- Any deficiency or overpayment should be charged or credited to deposit account number 13-1703. 8.
- 9. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Dated: July 9, 2002

07/17/2002 EHAILE1 00000014 10192800

04 FC:581

40.00 GP

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Alan T. McCollom

Reg. No. 28,881

MARGER JOHNSON & McCOLLOM, P.C. 1030 SW Morrison Street Portland, OR 97205 (503) 222-3613

Total number of pages comprising cover sheet and attached assignment: 3

PATENT APPLICATION Atty's Do. No. 9903-051 Yoon & Lee Ref. No.:

ASSIGNMENT

U.S.A. Patent Application
Sole or Joint
For Inventions Made Outside U.S.A.
Executed With Application

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- (1) Young-Hee SONG
- (2) Il-Heung CHOI
- (3) Jeong-Jin KIM
- (4) Hae-Jeong SOHN
- (5) Chung-Woo LEE

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(hereinafter designated "ASSIGNEE") the entire right, title and interest in and to the invention as defined in 35 USC §100, for the United States of America, the invention entitled:

SEMICONDUCTOR CHIP HAVING BOND PADS AND MULTI-CHIP PACKAGE

for which an application for Letters Patent of the United States of America has been executed even date herewith by the undersigned, and in and to any and all divisionals, continuations, substitutes, and reissues thereof; and all resulting patents and the undersigned hereby authorizes and requests the United States Assistant Commissioner of Patents to issue said Letters Patent to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

And the undersigned hereby agrees to testify and execute any papers for ASSIGNEE, its successors, assigns and legal representatives, deemed essential by ASSIGNEE to ASSIGNEE'S full protection and title in and to the invention hereby transferred.

Please sign
concurrently
with Oath or Declaration
and Power of Attorney

SIGNED ON THE DATES INDICATED BESIDE OUR SIGNATURES:

INVENTOR(S)	DATE SIGNED	WITNESSED
(1) Young-Hee SONG Young-Hee SONG	June 20 02	
(2) <u>IL. Heung CHOZ</u> Il-Heung CHOI	June . M. or	
(3) <u>Jeons-Jm Kim</u> Jeong-Jin KIM	Jue. 20 /02	
(4) Hac- Econy Sichon Hae-Jeong SOHN	June 2 '02.	
(5) Chung-Woo LEE Chung-Woo LEE	June . 20. 02	<u>:</u>

PLEASE RETURN RECORDED ASSIGNMENT TO:

Alan T. McCollom Marger Johnson & McCollom 1030 S.W. Morrison Street Portland, OR 97205